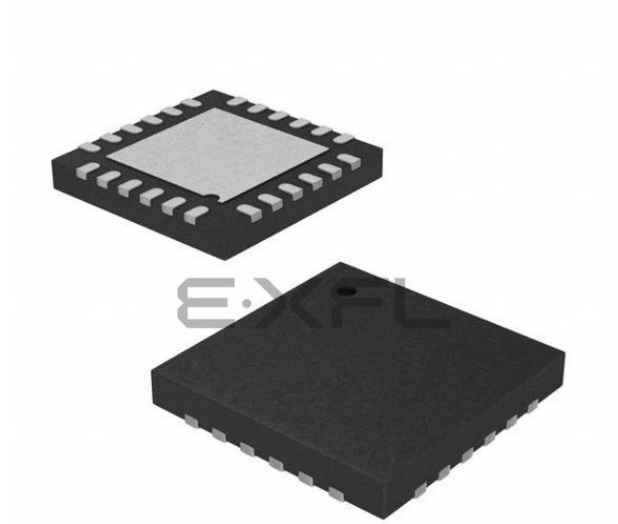


Welcome to E-XFL.COM

Embedded - Microcontrollers - Application Specific: Tailored Solutions for Precision and Performance

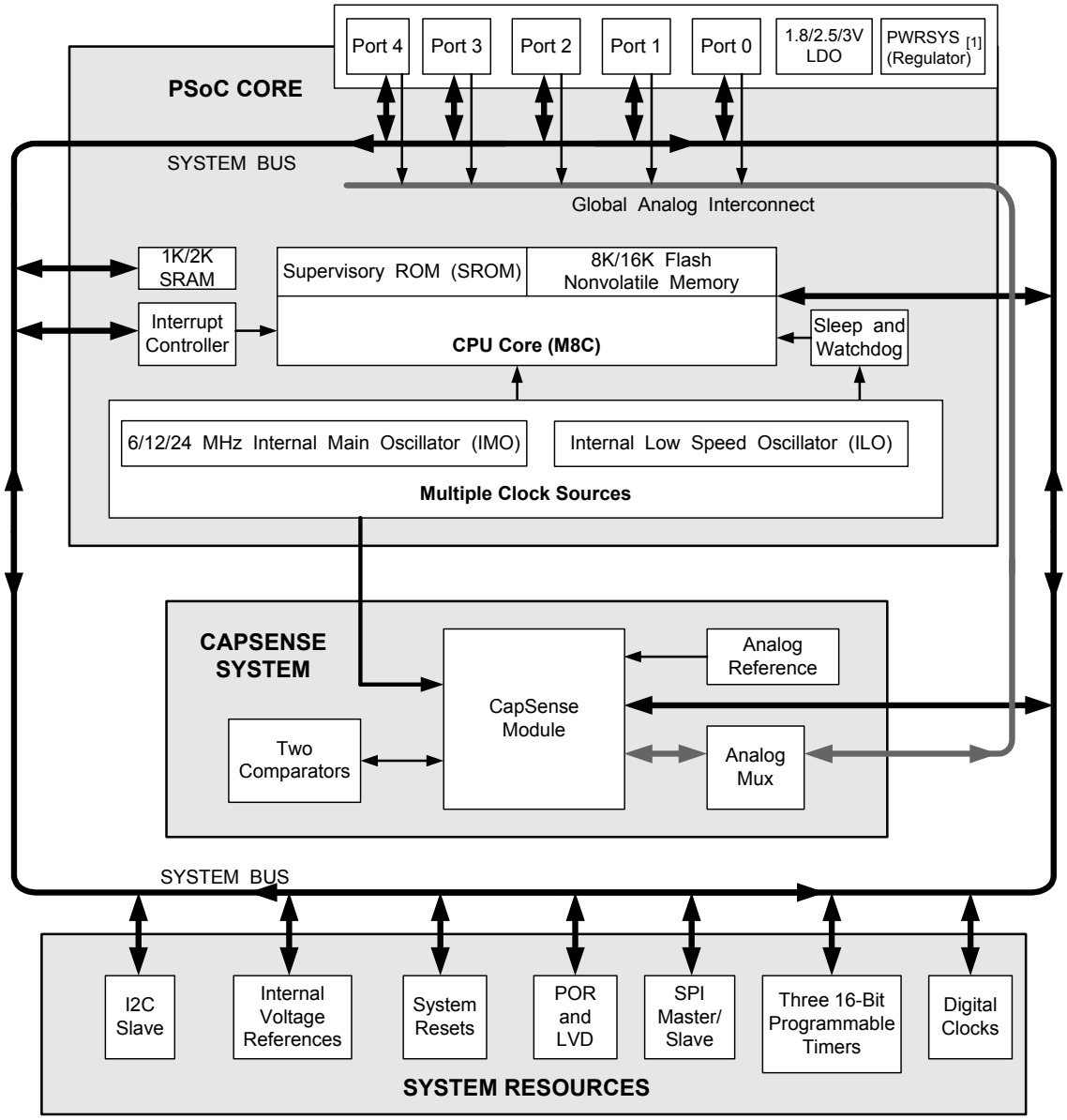
Embedded - Microcontrollers - Application Specific represents a category of microcontrollers designed with unique features and capabilities tailored to specific application needs. Unlike general-purpose microcontrollers, application-specific microcontrollers are optimized for particular tasks, offering enhanced performance, efficiency, and functionality to meet the demands of specialized applications.

What Are Embedded - Microcontrollers - Application Specific?

Application-specific microcontrollers are engineered to

Details	
Product Status	Active
Applications	Capacitive Sensing
Core Processor	M8C
Program Memory Type	FLASH (8kB)
Controller Series	CY8C20xx6A
RAM Size	1K x 8
Interface	I²C, SPI
Number of I/O	20
Voltage - Supply	1.71V ~ 5.5V
Operating Temperature	-40°C ~ 85°C (TC)
Mounting Type	Surface Mount
Package / Case	24-UFQFN Exposed Pad
Supplier Device Package	24-QFN (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/cy8c20336a-24lqxit

Logic Block Diagram



Note
1. Internal voltage regulator for internal circuitry

Contents

PSoC® Functional Overview

The PSoC family consists of on-chip controller devices, which are designed to replace multiple traditional microcontroller unit (MCU)-based components with one, low-cost single-chip programmable component. A PSoC device includes configurable analog and digital blocks, and programmable interconnect. This architecture allows the user to create customized peripheral configurations, to match the requirements of each individual application. Additionally, a fast CPU, flash program memory, SRAM data memory, and configurable I/O are included in a range of convenient pinouts.

The architecture for this device family, as shown in the Logic Block Diagram on page 2, consists of three main areas:

- The core
- CapSense analog system
- System resources (including a full-speed USB port).

A common, versatile bus allows connection between the I/O and the analog system.

Each CY8C20336H/446H PSoC device includes a dedicated CapSense block that provides sensing and scanning control circuitry for capacitive sensing applications. Depending on the PSoC package, up to 28 GPIOs are also included. The GPIOs provide access to the MCU and analog mux.

PSoC Core

The PSoC core is a powerful engine that supports a rich instruction set. It encompasses SRAM for data storage, an interrupt controller, sleep and watchdog timers, and IMO and ILO. The CPU core, called the M8C, is a powerful processor with speeds up to 24 MHz. The M8C is a 4-MIPS, 8-bit Harvard-architecture microprocessor.

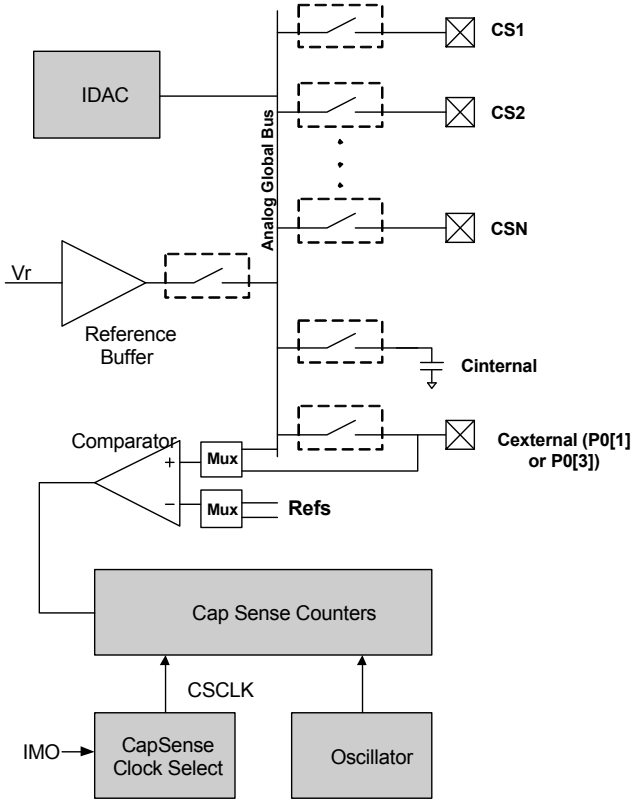
CapSense System

The analog system contains the capacitive sensing hardware. Several hardware algorithms are supported. This hardware performs capacitive sensing and scanning without requiring external components. The analog system is composed of the CapSense PSoC block and an internal 1-V or 1.2-V analog reference, which together support capacitive sensing of up to 28 inputs[2]. Capacitive sensing is configurable on each GPIO pin. Scanning of enabled CapSense pins are completed quickly and easily across multiple ports.

SmartSense™

SmartSense is an innovative solution from Cypress that removes manual tuning of CapSense applications. This solution is easy-to-use and provides a robust noise immunity. It is the only auto-tuning solution that establishes, monitors, and maintains all required tuning parameters. SmartSense allows engineers to go from prototyping to mass production without re-tuning for manufacturing variations in PCB and/or overlay material properties.

Figure 1. CapSense System Block Diagram



Analog Multiplexer System

The analog mux bus can connect to every GPIO pin. Pins are connected to the bus individually or in any combination. The bus also connects to the analog system for analysis with the CapSense block comparator.

Switch-control logic enables selected pins to precharge continuously under hardware control. This enables capacitive measurement for applications such as touch sensing. Other multiplexer applications include:

- Complex capacitive sensing interfaces, such as sliders and touchpads.
- Chip-wide mux that allows analog input from any I/O pin.
- Crosspoint connection between any I/O pin combinations.

Haptics TS2000 Controller

The CY8C20336H/CY8C20446H family of devices feature an easy-to-use Haptics controller resource with up to 14 different effects. These effects are available for use with three different, selectable ERM modules.

Note
2. 36 GPIOs = 33 pins for capacitive sensing + 2 pins for I^2C + 1 pin for modulator capacitor.

Additional System Resources

System resources provide additional capability, such as configurable USB and I^2C slave, SPI master/slave communication interface, three 16-bit programmable timers, and various system resets supported by the M8C.

These system resources provide additional capability useful to complete systems. Additional resources include low voltage detection and power on reset. The merits of each system resource are listed here:

- The I^2C slave/SPI master-slave module provides 50/100/400 kHz communication over two wires. SPI communication over three or four wires runs at speeds of 46.9 kHz to 3 MHz (lower for a slower system clock).
- The I^2C hardware address recognition feature reduces the already low power consumption by eliminating the need for CPU intervention until a packet addressed to the target device is received.
- The I^2C enhanced slave interface appears as a 32-byte RAM buffer to the external I^2C master. Using a simple predefined protocol, the master controls the read and write pointers into the RAM. When this method is enabled, the slave does not stall the bus when receiving data bytes in active mode. For usage details, refer to the application note I2C Enhanced Slave Operation - AN56007.
- Low voltage detection (LVD) interrupts can signal the application of falling voltage levels, while the advanced power-on-reset (POR) circuit eliminates the need for a system supervisor.
- An internal reference provides an absolute reference for capacitive sensing.
- A register-controlled bypass mode allows the user to disable the LDO regulator.

Getting Started

For in depth information, along with detailed programming details, see the PSoC® Technical Reference Manual.

For up-to-date ordering, packaging, and electrical specification information, see the latest PSoC device datasheets on the web.

Application Notes

Cypress application notes are an excellent introduction to the wide variety of possible PSoC designs.

Development Kits

PSoC Development Kits are available online from and through a growing number of regional and global distributors, which include Arrow, Avnet, Digi-Key, Farnell, Future Electronics, and Newark.

Training

Free PSoC technical training (on demand, webinars, and workshops), which is available online via www.cypress.com, covers a wide variety of topics and skill levels to assist you in your designs.

CYPros Consultants

Certified PSoC consultants offer everything from technical assistance to completed PSoC designs. To contact or become a PSoC consultant go to the CYPros Consultants web site.

Solutions Library

Visit our growing library of solution focused designs. Here you can find various application designs that include firmware and hardware design files that enable you to complete your designs quickly.

Technical Support

Technical support – including a searchable Knowledge Base articles and technical forums – is also available online. If you cannot find an answer to your question, call our Technical Support hotline at 1-800-541-4736.

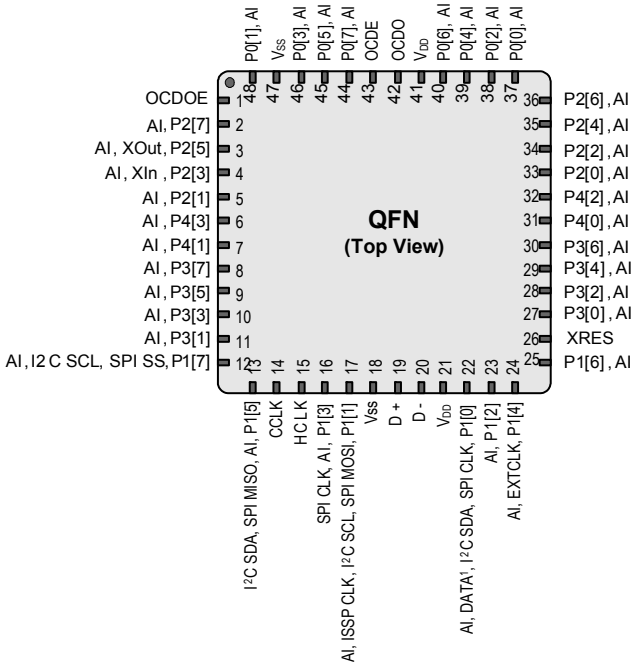
48-Pin QFN OCD

The 48-pin QFN part is for the CY8C20066A On-Chip Debug (OCD) PSoC device. Note that this part is only used for in-circuit debugging.[9]

Table 3. Pin Definitions - CY8C20066A PSoC Device [10, 11]

Pin No.	Digital	Analog	Name	Description
1			OCDOE	OCD mode direction pin
2	I/O	I	P2[7]	
3	I/O	I	P2[5]	Crystal output (XOut)
4	I/O	I	P2[3]	Crystal input (XIn)
5	I/O	I	P2[1]	
6	I/O	I	P4[3]	
7	I/O	I	P4[1]	
8	I/O	I	P3[7]	
9	I/O	I	P3[5]	
10	I/O	I	P3[3]	
11	I/O	I	P3[1]	
12	IOHR	I	P1[7]	I^2C SCL, SPI SS
13	IOHR	I	P1[5]	I^2C SDA, SPI MISO
14			CCLK	OCD CPU clock output
15			HCLK	OCD high speed clock output
16	IOHR	I	P1[3]	SPI CLK.
17	IOHR	I	P1[1]	ISSP CLK[12], I^2C SCL, SPI MOSI
18	Power		Vss	Ground connection
19	I/O		D+	USB D+
20	I/O		D-	USB D-
21	Power		V_{DD}	Supply voltage
22	IOHR	I	P1[0]	ISSP DATA[12], I^2C SDA, SPI CLK
23	IOHR	I	P1[2]	
24	IOHR	I	P1[4]	Optional external clock input (EXTCLK)
25	IOHR	I	P1[6]	
26	Input		XRES	Active high external reset with internal pull down
27	I/O	I	P3[0]	
28	I/O	I	P3[2]	
29	I/O	I	P3[4]	
30	I/O	I	P3[6]	
31	I/O	I	P4[0]	
32	I/O	I	P4[2]	
33	I/O	I	P2[0]	
34	I/O	I	P2[2]	
35	I/O	I	P2[4]	
36	I/O	I	P2[6]	
37	IOH	I	P0[0]	
38	IOH	I	P0[2]	
39	IOH	I	P0[4]	
40	IOH	I	P0[6]	
41	Power		V_{DD}	Supply voltage
42			OCDO	OCD even data I/O
43			OCDE	OCD odd data output
44	IOH	I	P0[7]	
45	IOH	I	P0[5]	
46	IOH	I	P0[3]	Integrating input
47	Power		V_{SS}	Ground connection
48	IOH	I	P0[1]	
CP	Power		V_{SS}	Center pad must be connected to ground

Figure 4. CY8C20066A PSoC Device



LEGEND A = Analog, I = Input, O = Output, NC = No Connection H = 5 mA High Output Drive, R = Regulated Output.

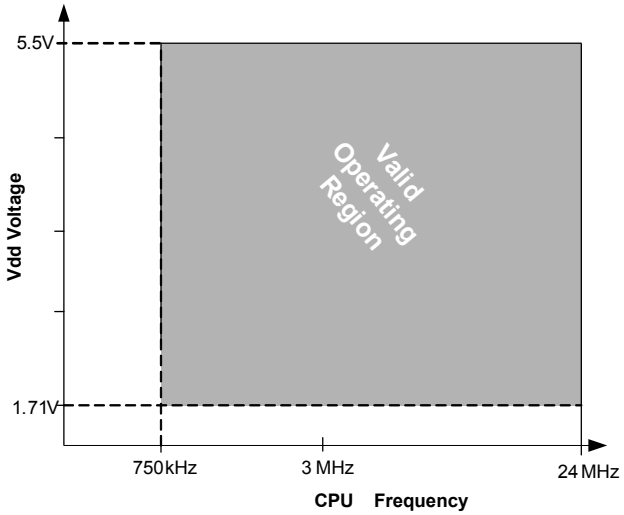
Notes

9. This part is available in limited quantities for In-Circuit Debugging during prototype development. It is not available in production volumes.
10. During power-up or reset event, device P1[1] and P1[0] may disturb the I^2C bus. Use alternate pins if you encounter any issues.
11. The center pad (CP) on the QFN package must be connected to ground (Vss) for best mechanical, thermal, and electrical performance. If not connected to ground, it must be electrically floated and not connected to any other signal.
12. These are the ISSP pins, which are not High Z at power on reset (POR).

Electrical Specifications

This section presents the DC and AC electrical specifications of the CY8C20x36H/46H PSoC devices. For the latest electrical specifications, confirm that you have the most recent data sheet by visiting the web at http://www.cypress.com/psoc.

Figure 5. Voltage versus CPU Frequency



Absolute Maximum Ratings

Exceeding maximum ratings may shorten the useful life of the device. User guidelines are not tested.

Table 4. Absolute Maximum Ratings

Symbol	Description	Conditions	Min	Typ	Max	Units
T_{STG}	Storage temperature	Higher storage temperatures reduce data retention time. Recommended Storage Temperature is +25 °C ± 25 °C. Extended duration storage temperatures above 85 °C degrades reliability.	–55	+25	+125	°C
V_{DD}	Supply voltage relative to V_{SS}		–0.5	–	+6.0	V
V_{IO}	DC input voltage		V_{SS} – 0.5	–	V_{DD} + 0.5	V
V_{IOZ}	DC voltage applied to tristate		V_{SS} –0.5	–	V_{DD} + 0.5	V
I_{MIO}	Maximum current into any port pin		–25	–	+50	mA
ESD	Electrostatic discharge voltage	Human body model ESD	2000	–	–	V
LU	Latch up current	In accordance with JESD78 standard	–	–	200	mA

Operating Temperature

Table 5. Operating Temperature

Symbol	Description	Conditions	Min	Typ	Max	Units
T_A	Ambient temperature		–40	–	+85	°C
T_C	Commercial temperature range		0	–	70	°C
T_J	Operational die temperature	The temperature rise from ambient to junction is package specific. Refer the table Thermal Impedances per Package on page 28. The user must limit the power consumption to comply with this requirement.	–40	–	+100	°C

DC General Purpose I/O Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 3.0 V to 5.5 V and –40 °C ≤ T_A ≤ 85°C, 2.4 V to 3.0 V and –40 °C ≤ T_A ≤ 85 °C, or 1.71 V to 2.4 V and –40 °C ≤ T_A ≤ 85 °C, respectively. Typical parameters apply to 5 V and 3.3 V at 25 °C and are for design guidance only.

Table 7. 3.0 V to 5.5 V DC GPIO Specifications

Symbol	Description	Conditions	Min	Typ	Max	Units
R_{PU}	Pull-up resistor		4	5.60	8	kΩ
V_{OH1}	High output voltage port 2 or 3 pins	I_{OH} ≤ 10 µA, maximum of 10 mA source current in all I/Os	V_{DD} – 0.20	–	–	V
V_{OH2}	High output voltage port 2 or 3 pins	I_{OH} = 1 mA, maximum of 20 mA source current in all I/Os	V_{DD} – 0.90	–	–	V
V_{OH3}	High output voltage port 0 or 1 pins with LDO regulator disabled for port 1	I_{OH} < 10 µA, maximum of 10 mA source current in all I/Os	V_{DD} – 0.20	–	–	V
V_{OH4}	High output voltage port 0 or 1 pins with LDO regulator disabled for port 1	I_{OH} = 5 mA, maximum of 20 mA source current in all I/Os	V_{DD} – 0.90	–	–	V
V_{OH5}	High output voltage port 1 pins with LDO regulator enabled for 3 V out	I_{OH} < 10 µA, V_{DD} > 3.1 V, maximum of 4 I/Os all sourcing 5 mA	2.85	3.00	3.30	V
V_{OH6}	High output voltage port 1 pins with LDO regulator enabled for 3 V out	I_{OH} = 5 mA, V_{DD} > 3.1 V, maximum of 20 mA source current in all I/Os	2.20	–	–	V
V_{OH7}	High output voltage port 1 pins with LDO enabled for 2.5 V out	I_{OH} < 10 µA, V_{DD} > 2.7 V, maximum of 20 mA source current in all I/Os	2.35	2.50	2.75	V
V_{OH8}	High output voltage port 1 pins with LDO enabled for 2.5 V out	I_{OH} = 2 mA, V_{DD} > 2.7 V, maximum of 20 mA source current in all I/Os	1.90	–	–	V
V_{OH9}	High output voltage port 1 pins with LDO enabled for 1.8 V out	I_{OH} < 10 µA, V_{DD} > 2.7 V, maximum of 20 mA source current in all I/Os	1.60	1.80	2.10	V
V_{OH10}	High output voltage port 1 pins with LDO enabled for 1.8 V out	I_{OH} = 1 mA, V_{DD} > 2.7 V, maximum of 20 mA source current in all I/Os	1.20	–	–	V
V_{OL}	Low output voltage	I_{OL} = 25 mA, V_{DD} > 3.3 V, maximum of 60 mA sink current on even port pins (for example, P0[2] and P1[4]) and 60 mA sink current on odd port pins (for example, P0[3] and P1[5])	–	–	0.75	V
V_{IL}	Input low voltage		–	–	0.80	V
V_{IH}	Input high voltage		2.00	–	–	V
V_H	Input hysteresis voltage		–	80	–	mV
I_{IL}	Input leakage (absolute value)		–	0.001	1	µA
C_{PIN}	Pin capacitance	Package and pin dependent Temp = 25 °C	0.50	1.70	7	pF

Table 8. 2.4 V to 3.0 V DC GPIO Specifications

Symbol	Description	Conditions	Min	Typ	Max	Units
R_{PU}	Pull-up resistor		4	5.60	8	kΩ
V_{OH1}	High output voltage port 2 or 3 pins	I_{OH} < 10 µA, maximum of 10 mA source current in all I/Os	V_{DD} – 0.20	–	–	V
V_{OH2}	High output voltage port 2 or 3 pins	I_{OH} = 0.2 mA, maximum of 10 mA source current in all I/Os	V_{DD} – 0.40	–	–	V
V_{OH3}	High output voltage port 0 or 1 pins with LDO regulator disabled for port 1	I_{OH} < 10 µA, maximum of 10 mA source current in all I/Os	V_{DD} – 0.20	–	–	V
V_{OH4}	High output voltage port 0 or 1 pins with LDO regulator disabled for port 1	I_{OH} = 2 mA, maximum of 10 mA source current in all I/Os	V_{DD} – 0.50	–	–	V
V_{OH5A}	High output voltage port 1 pins with LDO enabled for 1.8 V out	I_{OH} < 10 µA, V_{DD} > 2.4 V, maximum of 20 mA source current in all I/Os	1.50	1.80	2.10	V
V_{OH6A}	High output voltage port 1 pins with LDO enabled for 1.8 V out	I_{OH} = 1 mA, V_{DD} > 2.4 V, maximum of 20 mA source current in all I/Os	1.20	–	–	V
V_{OL}	Low output voltage	I_{OL} = 10 mA, maximum of 30 mA sink current on even port pins (for example, P0[2] and P1[4]) and 30 mA sink current on odd port pins (for example, P0[3] and P1[5])	–	–	0.75	V
V_{IL}	Input low voltage		–	–	0.72	V
V_{IH}	Input high voltage		1.40	–	–	V
V_H	Input hysteresis voltage		–	80	–	mV
I_{IL}	Input leakage (absolute value)		–	1	1000	nA
C_{PIN}	Capacitive load on pins	Package and pin dependent Temp = 25 °C	0.50	1.70	7	pF

Table 9. 1.71 V to 2.4 V DC GPIO Specifications

Symbol	Description	Conditions	Min	Typ	Max	Units
R_{PU}	Pull-up resistor		4	5.60	8	kΩ
V_{OH1}	High output voltage port 2 or 3 pins	I_{OH} = 10 µA, maximum of 10 mA source current in all I/Os	V_{DD} – 0.20	–	–	V
V_{OH2}	High output voltage port 2 or 3 pins	I_{OH} = 0.5 mA, maximum of 10 mA source current in all I/Os	V_{DD} – 0.50	–	–	V
V_{OH3}	High output voltage port 0 or 1 pins with LDO regulator disabled for port 1	I_{OH} = 100 µA, maximum of 10 mA source current in all I/Os	V_{DD} – 0.20	–	–	V
V_{OH4}	High output voltage port 0 or 1 pins with LDO regulator disabled for port 1	I_{OH} = 2 mA, maximum of 10 mA source current in all I/Os	V_{DD} – 0.50	–	–	V
V_{OL}	Low output voltage	I_{OL} = 5 mA, maximum of 20 mA sink current on even port pins (for example, P0[2] and P1[4]) and 30 mA sink current on odd port pins (for example, P0[3] and P1[5])	–	–	0.40	V
V_{IL}	Input low voltage		–	–	0.30 × V_{DD}	V
V_{IH}	Input high voltage		0.65 × V_{DD}	–	–	V

Comparator User Module Electrical Specifications

The following table lists the guaranteed maximum and minimum specifications. Unless stated otherwise, the specifications are for the entire device voltage and temperature operating range: –40 °C ≤ TA ≤ 85 °C, 1.71 V ≤ V_{DD} ≤ 5.5 V.

Table 13. Comparator User Module Electrical Specifications

Symbol	Description	Conditions	Min	Typ	Max	Units
T_{COMP}	Comparator response time	50-mV overdrive	–	70	100	ns
Offset		Valid from 0.2 V to V_{DD} – 0.2 V	–	2.5	30	mV
Current		Average DC current, 50 mV overdrive	–	20	80	µA
PSRR	Supply voltage > 2 V	Power supply rejection ratio	–	80	–	dB
	Supply voltage < 2 V	Power supply rejection ratio	–	40	–	dB
Input Range			0	–	1.5	V

ADC Electrical Specifications

Table 14.ADC User Module Electrical Specifications

Symbol	Description	Conditions	Min	Typ	Max	Units
Input						
V_{IN}	Input voltage range		0	–	VREFADC	V
C_{IIN}	Input capacitance		–	–	5	pF
R_{IN}	Input resistance	Equivalent switched cap input resistance for 8-, 9-, or 10-bit resolution	1/(500fF × data clock)	1/(400fF × data clock)	1/(300fF × data clock)	Ω
Reference						
V_{REFADC}	ADC reference voltage		1.14	–	1.26	V
Conversion Rate						
F_{CLK}	Data clock	Source is chip's internal main oscillator. See AC Chip-Level Specifications on page 18 for accuracy	2.25	–	6	MHz
S8	8-bit sample rate	Data clock set to 6 MHz. Sample Rate = 0.001/ (2^Resolution/Data clock)	–	23.43	–	ksps
S10	10-bit sample rate	Data clock set to 6 MHz. Sample Rate = 0.001/ (2^Resolution/Data clock)	–	5.85	–	ksps
DC Accuracy						
RES	Resolution	Can be set to 8-, 9-, or 10-bit	8	–	10	bits
DNL	Differential nonlinearity		–1	–	+2	LSB
INL	Integral nonlinearity		–2	–	+2	LSB
E_{OFFSET}	Offset error	8-bit resolution	0	3.20	19.20	LSB
		10-bit resolution	0	12.80	76.80	LSB
E_{GAIN}	Gain error	For any resolution	–5	–	+5	%FSR
Power						
I_{ADC}	Operating current		–	2.10	2.60	mA
PSRR	Power supply rejection ratio	PSRR (V_{DD} > 3.0 V)	–	24	–	dB
		PSRR (V_{DD} < 3.0 V)	–	30	–	dB

DC POR and LVD Specifications

The following table lists guaranteed maximum and minimum specifications for the entire voltage and temperature ranges.

Table 15. DC POR and LVD Specifications

Symbol	Description	Conditions	Min	Typ	Max	Units
V_{POR0}	1.66 V selected in PSoC Designer	V_{DD} must be greater than or equal to 1.71 V during startup, reset from the XRES pin, or reset from watchdog.	1.61	1.66	1.71	V
V_{POR1}	2.36 V selected in PSoC Designer		–	2.36	2.41	
V_{POR2}	2.60 V selected in PSoC Designer		–	2.60	2.66	
V_{POR3}	2.82 V selected in PSoC Designer		–	2.82	2.95	
V_{LVD0}	2.45 V selected in PSoC Designer		2.40	2.45	2.51	V
V_{LVD1}	2.71 V selected in PSoC Designer		2.64[14]	2.71	2.78	
V_{LVD2}	2.92 V selected in PSoC Designer		2.85[15]	2.92	2.99	
V_{LVD3}	3.02 V selected in PSoC Designer		2.95[16]	3.02	3.09	
V_{LVD4}	3.13 V selected in PSoC Designer		3.06	3.13	3.20	
V_{LVD5}	1.90 V selected in PSoC Designer		1.84	1.90	2.32	
V_{LVD6}	1.80 V selected in PSoC Designer		1.75[17]	1.80	1.84	
V_{LVD7}	4.73 V selected in PSoC Designer		4.62	4.73	4.83	

DC Programming Specifications

The following table lists guaranteed maximum and minimum specifications for the entire voltage and temperature ranges.

Table 16. DC Programming Specifications

Symbol	Description	Conditions	Min	Typ	Max	Units
Vdd_{IWRITE}	Supply voltage for flash write operations		1.71	–	5.25	V
I_{DDP}	Supply current during programming or verify		–	5	25	mA
V_{ILP}	Input low voltage during programming or verify	See the appropriate DC General Purpose I/O Specifications on page 13	–	–	V_{IL}	V
V_{IHP}	Input high voltage during programming or verify	See appropriate DC General Purpose I/O Specifications on page 13 table on pages 15 or 16	V_{IH}	–	–	V
I_{ILP}	Input current when applying V_{ILP} to P1[0] or P1[1] during programming or verify	Driving internal pull-down resistor	–	–	0.2	mA
I_{IHP}	Input current when applying V_{IHP} to P1[0] or P1[1] during programming or verify	Driving internal pull-down resistor	–	–	1.5	mA
V_{OLP}	Output low voltage during programming or verify		–	–	V_{SS} + 0.75	V
V_{OHP}	Output high voltage during programming or verify	See appropriate DC General Purpose I/O Specifications on page 13 table on page 16. For V_{DD} > 3 V use V_{OH4} in Table 5 on page 11.	V_{OH}	–	V_{DD}	V
$Flash_{ENPB}$	Flash write endurance	Erase/write cycles per block	50,000	–	–	-
$Flash_{DR}$	Flash data retention	Following maximum flash write cycles; ambient temperature of 55 °C	10	20	–	Years

Notes
14. Always greater than 50 mV above V_{PPOR1} voltage for falling supply.
15. Always greater than 50 mV above V_{PPOR2} voltage for falling supply.
16. Always greater than 50 mV above V_{PPOR3} voltage for falling supply.
17. Always greater than 50 mV above V_{PPOR0} voltage for falling supply.

AC General Purpose I/O Specifications

The following table lists guaranteed maximum and minimum specifications for the entire voltage and temperature ranges.

Table 18. AC GPIO Specifications

Symbol	Description	Conditions	Min	Typ	Max	Units
F_{GPIO}	GPIO operating frequency	Normal strong mode port 0, 1	0 0	– –	6 MHz for 1.71 V <V_{DD} < 2.40 V 12 MHz for 2.40 V < V_{DD}< 5.50 V	MHz
T_{RISE23}	Rise time, strong mode, Cload = 50 pF ports 2 or 3	V_{DD} = 3.0 to 3.6 V, 10% – 90%	15	–	80	ns
$T_{RISE23L}$	Rise time, strong mode low supply, Cload = 50 pF, ports 2 or 3	V_{DD} = 1.71 to 3.0 V, 10% – 90%	15	–	80	ns
T_{RISE01}	Rise time, strong mode, Cload = 50 pF ports 0 or 1	V_{DD} = 3.0 to 3.6 V, 10% – 90% LDO enabled or disabled	10	–	50	ns
$T_{RISE01L}$	Rise time, strong mode low supply, Cload = 50 pF, ports 0 or 1	V_{DD} = 1.71 to 3.0 V, 10% – 90% LDO enabled or disabled	10	–	80	ns
T_{FALL}	Fall time, strong mode, Cload = 50 pF all ports	V_{DD} = 3.0 to 3.6 V, 10% – 90%	10	–	50	ns
T_{FALLL}	Fall time, strong mode low supply, Cload = 50 pF, all ports	V_{DD} = 1.71 to 3.0 V, 10% – 90%	10	–	70	ns

Figure 6. GPIO Timing Diagram

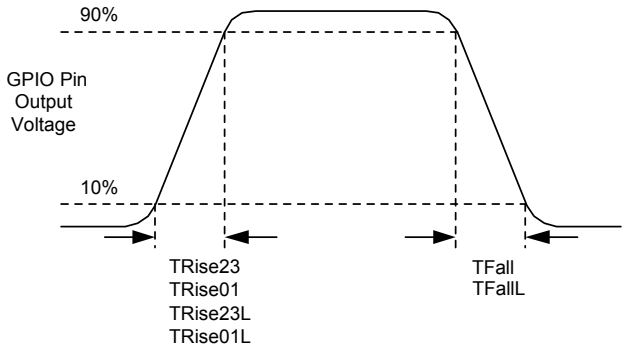


Table 19.AC Characteristics – USB Data Timings

Symbol	Description	Conditions	Min	Typ	Max	Units
T_{DRATE}	Full-speed data rate	Average bit rate	12 – 0.25%	12	12 + 0.25%	MHz
T_{JR1}	Receiver jitter tolerance	To next transition	–18.5	–	18.5	ns
T_{JR2}	Receiver jitter tolerance	To pair transition	–9	–	9	ns
T_{DJ1}	FS driver jitter	To next transition	–3.5	–	3.5	ns
T_{DJ2}	FS driver jitter	To pair transition	–4.0	–	4.0	ns
T_{FDEOP}	Source jitter for differential transition	To SE0 transition	–2	–	5	ns
T_{FEOPT}	Source SE0 interval of EOP		160	–	175	ns
T_{FEOPR}	Receiver SE0 interval of EOP		82	–		ns
T_{FST}	Width of SE0 interval during differential transition		–	–	14	ns

Table 20. AC Characteristics – USB Driver

Symbol	Description	Conditions	Min	Typ	Max	Units
T_{FR}	Transition rise time	50 pF	4	–	20	ns
T_{FF}	Transition fall time	50 pF	4	–	20	ns
T_{FRFM}[19]	Rise/fall time matching		90	–	111	%
Vcrs	Output signal crossover voltage		1.30	–	2.00	V

AC Comparator Specifications

The following table lists guaranteed maximum and minimum specifications for the entire voltage and temperature ranges.

Table 21. AC Low Power Comparator Specifications

Symbol	Description	Conditions	Min	Typ	Max	Units
T_{LPC}	Comparator response time, 50 mV overdrive	50 mV overdrive does not include offset voltage.	–	–	100	ns

AC External Clock Specifications

The following table lists guaranteed maximum and minimum specifications for the entire voltage and temperature ranges.

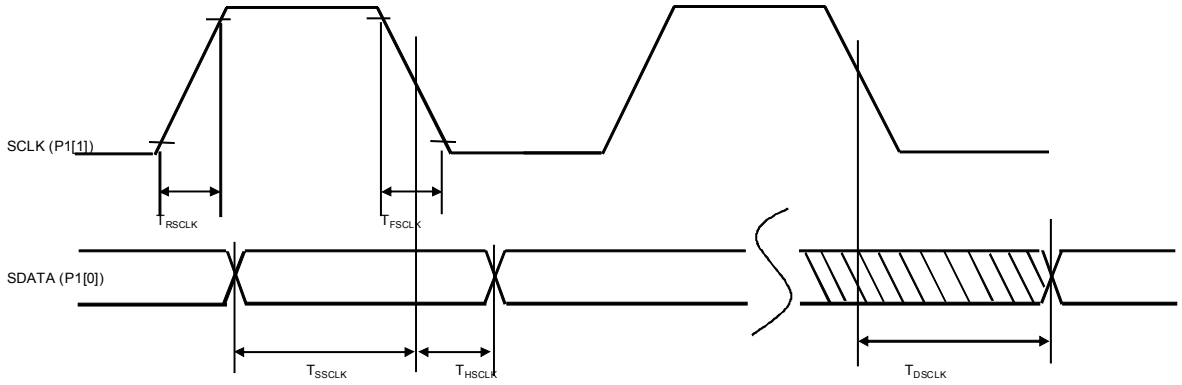
Table 22. AC External Clock Specifications

Symbol	Description	Conditions	Min	Typ	Max	Units
F_{OSCEXT}	Frequency (external oscillator frequency)		0.75	–	25.20	MHz
	High period		20.60	–	5300	ns
	Low period		20.60	–	–	ns
	Power-up IMO to switch		150	–	–	µs

Note
19. T_{FRFM} is not met under all conditions. There is a corner case at lower supply voltages, such as those under 3.3 V. This condition does not affect USB communications. Signal integrity tests show an excellent eye diagram at 3.15 V.

AC Programming Specifications

Figure 7. AC Waveform



The following table lists the guaranteed maximum and minimum specifications for the entire voltage and temperature ranges.

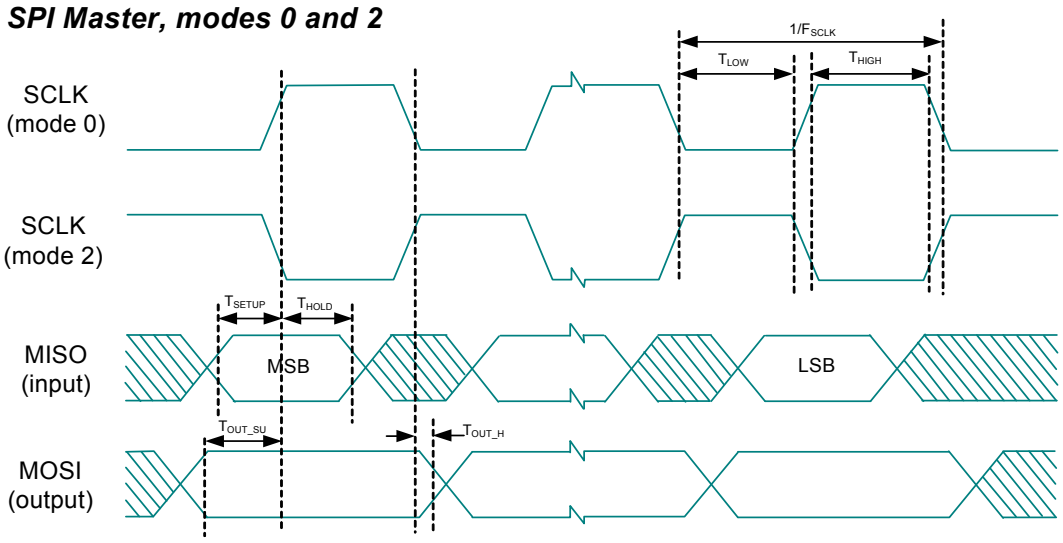
Table 23. AC Programming Specifications

Symbol	Description	Conditions	Min	Typ	Max	Units
T_{RSCLK}	Rise time of SCLK		1	–	20	ns
T_{FSCLK}	Fall time of SCLK		1	–	20	ns
T_{SSCLK}	Data Setup time to falling edge of SCLK		40	–	–	ns
T_{HSCLK}	Data Hold time from falling edge of SCLK		40	–	–	ns
F_{SCLK}	Frequency of SCLK		0	–	8	MHz
T_{ERASEB}	Flash erase time (Block)		–	–	18	ms
T_{WRITE}	Flash block write time		–	–	25	ms
T_{DSCLK}	Data out delay from falling edge of SCLK	$3.6 < V_{DD}$	–	–	60	ns
T_{DSCLK3}	Data out delay from falling edge of SCLK	$3.0 \le V_{DD} \le 3.6$	–	–	85	ns
T_{DSCLK2}	Data out delay from falling edge of SCLK	$1.71 \le V_{DD} \le 3.0$	–	–	130	ns
T_{XRST3}	External reset pulse width after power-up	Required to enter programming mode when coming out of sleep	300	–	–	µs
T_{XRES}	XRES Pulse Length		300	–	–	µs
$T_{VDDWAIT}$	V_{DD} stable to wait-and-poll hold off		0.1	–	1	ms
$T_{VDDXRES}$	V_{DD} stable to XRES assertion delay		14.27	–	–	ms
T_{POLL}	SDATA high pulse time		0.01	–	200	ms
T_{ACQ}	“Key window” time after a V_{DD} ramp acquire event, based on 256 ILO clocks.		3.20	–	19.60	ms
$T_{XRESINI}$	“Key window” time after an XRES event, based on eight ILO clocks		98	–	615	µs

Table 25. SPI Master AC Specifications

Symbol	Description	Conditions	Min	Typ	Max	Units
F_{SCLK}	SCLK clock frequency	$V_{DD} \geq 2.4$ V $V_{DD} < 2.4$ V	– –	– –	6 3	MHz
DC	SCLK duty cycle		–	50	–	%
T_{SETUP}	MISO to SCLK setup time	$V_{DD} \geq 2.4$ V $V_{DD} < 2.4$ V	60 100	– –	– –	ns
T_{HOLD}	SCLK to MISO hold time		40	–	–	ns
T_{OUT_VAL}	SCLK to MOSI valid time		–	–	40	ns
T_{OUT_H}	MOSI high time		40	–	–	ns

Figure 9. SPI Master Mode 0 and 2

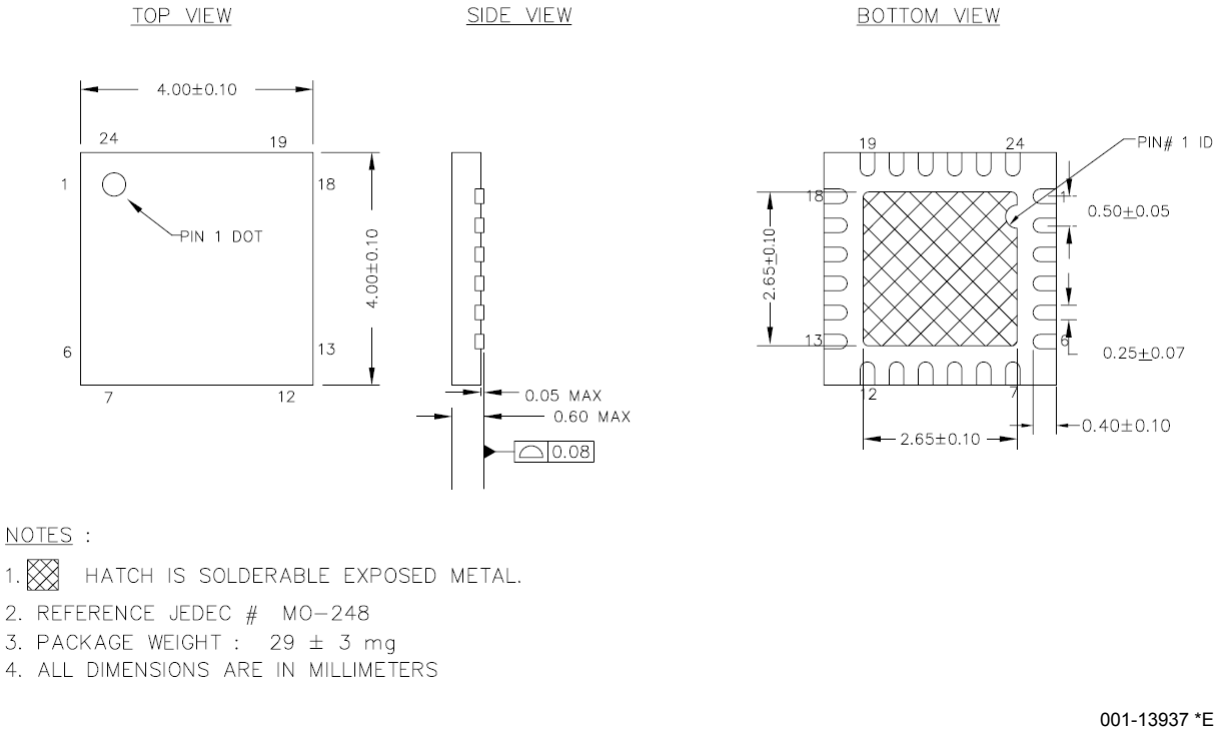


Packaging Information

This section illustrates the packaging specifications for the CY8C20336H/CY8C20446H PSoC device, along with the thermal impedances for each package.

Important Note Emulation tools may require a larger area on the target PCB than the chip's footprint. For a detailed description of the emulation tools' dimensions, refer to the document titled *PSoC Emulator Pod Dimensions* at http://www.cypress.com/design/MR10161.

Figure 13. 24-Pin (4 × 4 × 0.55 mm) QFN

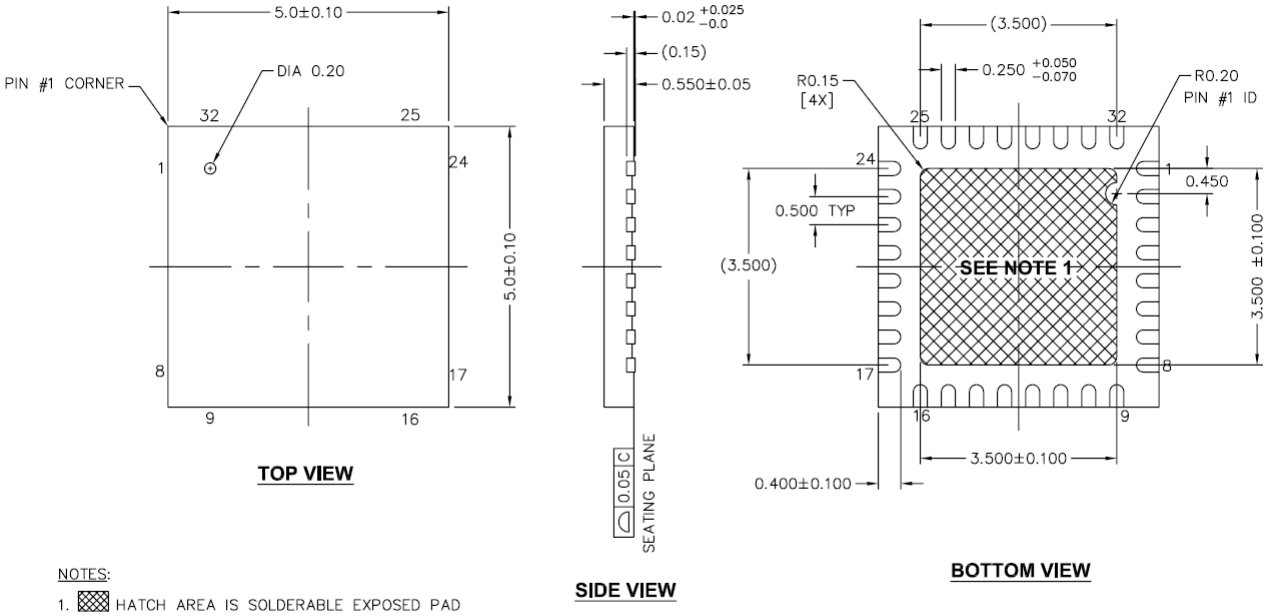


NOTES :

1. HATCH IS SOLDERABLE EXPOSED METAL.
2. REFERENCE JEDEC # MO-248
3. PACKAGE WEIGHT : 29 ± 3 mg
4. ALL DIMENSIONS ARE IN MILLIMETERS

001-13937 *E

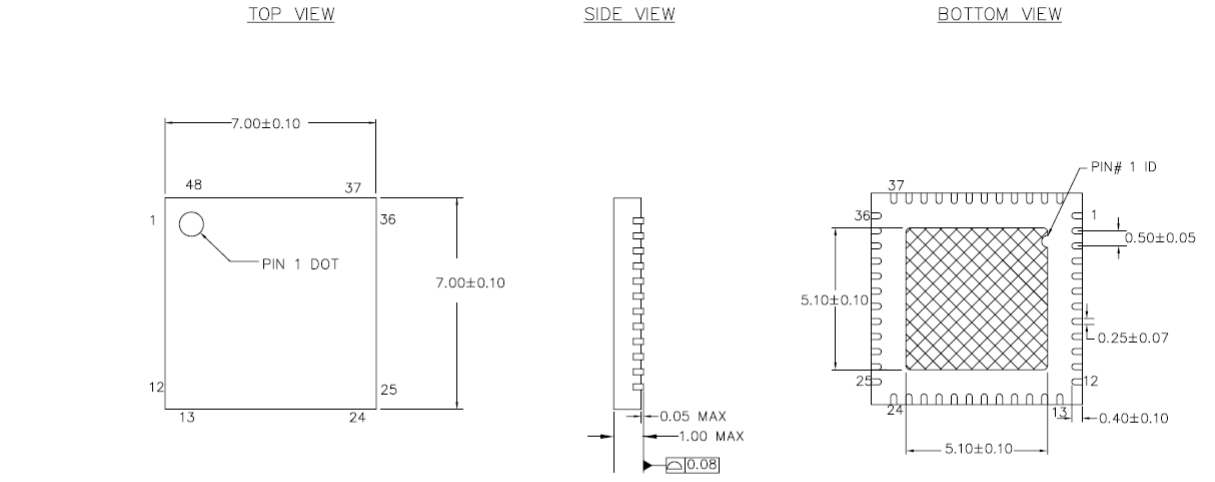
Figure 14. 32-Pin (5 × 5 × 0.55 mm) QFN



NOTES:
1. HATCH AREA IS SOLDERABLE EXPOSED PAD
2. BASED ON REF JEDEC # MO−248
3. PACKAGE WEIGHT: 0.0388g
4. DIMENSIONS ARE IN MILLIMETERS

001-42168 *E

Figure 15. 48-Pin (7 × 7 × 1.0 mm) QFN



NOTES:
1. HATCH AREA IS SOLDERABLE EXPOSED METAL.
2. REFERENCE JEDEC#: MO−220
3. PACKAGE WEIGHT: 13 ± 1 mg
4. ALL DIMENSIONS ARE IN MILLIMETERS

001-13191 *G

Important Notes

- For information on the preferred dimensions for mounting QFN packages, see the following Application Note at http://www.amkor.com/products/notes_papers/MLFAppNote.pdf.
- Pinned vias for thermal conduction are not required for the low power PSoC device.

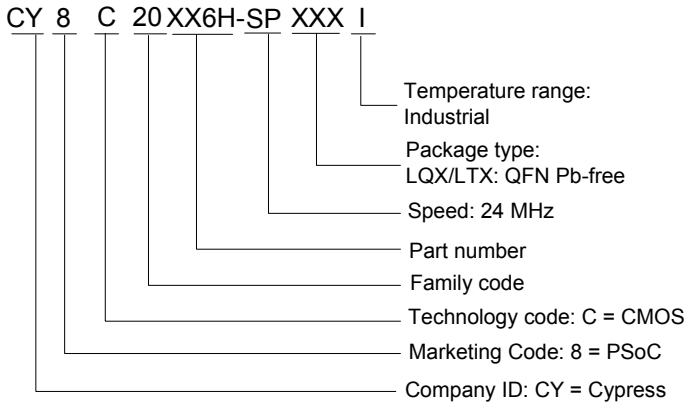
Ordering Information

The following table lists the CY8C20336H/CY8C20446H PSoC devices' key package features and ordering codes.

Table 31. PSoC Device Key Features and Ordering Information

Package	Ordering Code	Flash (KB)	SRAM (KB)	CapSense Blocks	Digital I/O Pins	Analog Inputs[27]	XRES Pin	USB
24-pin (4 × 4 × 0.6mm) QFN	CY8C20336H-24LQXI	8	1	1	20	20	Yes	No
32 pin (5 × 5 × 0.6 mm) QFN	CY8C20446H-24LQXI	16	2	1	28	28	Yes	No
48 pin (7 × 7 mm) QFN (OCD)[28]	CY8C20066A-24LTXI	32	2	1	36	36	Yes	Yes

Ordering Code Definitions



Document Conventions

Acronyms Used

The following table lists the acronyms that are used in this document.

Acronym	Description
AC	alternating current
ADC	analog-to-digital converter
API	application programming interface
CMOS	complementary metal oxide semiconductor
CPU	central processing unit
DAC	digital-to-analog converter
DC	direct current
EOP	end of packet
FSR	full scale range
GPIO	general purpose input/output
GUI	graphical user interface
I^2C	inter-integrated circuit
ICE	in-circuit emulator
IDAC	digital analog converter current
ILO	internal low speed oscillator
IMO	internal main oscillator
I/O	input/output
ISSP	in-system serial programming
LCD	liquid crystal display
LDO	low dropout (regulator)
LSB	least-significant bit
LVD	low voltage detect
MCU	micro-controller unit
MIPS	mega instructions per second
MISO	master in slave out
MOSI	master out slave in
MSB	most-significant bit
OCD	on-chip debugger
POR	power on reset
PPOR	precision power on reset
PSRR	power supply rejection ratio
PWRSYS	power system
PSoC®	Programmable System-on-Chip
SLIMO	slow internal main oscillator
SRAM	static random access memory
SNR	signal to noise ratio
QFN	quad flat no-lead
SCL	serial I^2C clock
SDA	serial I^2C data
SDATA	serial ISSP data
SPI	serial peripheral interface
SS	slave select
SSOP	shrink small outline package
TC	test controller
USB	universal serial bus
USB D+	USB Data +
USB D-	USB Data-
WLCSP	wafer level chip scale package
XTAL	crystal

Units of Measure

Table 32 lists all the abbreviations used to measure the PSoC devices.

Numeric Naming

Hexadecimal numbers are represented with all letters in uppercase with an appended lowercase ‘h’ (for example, ‘14h’ or ‘3Ah’). Hexadecimal numbers may also be represented by a ‘0x’ prefix, the C coding convention. Binary numbers have an appended lowercase ‘b’ (for example, 01010100b’ or ‘01000011b’). Numbers not indicated by an ‘h’, ‘b’, or 0x are decimal.

Table 32. Units of Measure

Symbol	Unit of Measure
°C	degree Celsius
dB	decibels
fF	femto farad
g	gram
Hz	hertz
KB	1024 bytes
Kbit	1024 bits
KHz	kilohertz
Ksps	kilo samples per second
kΩ	kilohm
MHz	megahertz
MΩ	megaohm
µA	microampere
µF	microfarad
µH	microhenry
µs	microsecond
µW	microwatts
mA	milli-ampere
ms	milli-second
mV	milli-volts
nA	nanoampere
ns	nanosecond
nV	nanovolts
Ω	ohm
pA	picoampere
pF	picofarad
pp	peak-to-peak
ppm	parts per million
ps	picosecond
sps	samples per second
s	sigma: one standard deviation
V	volts
W	watt

Glossary

Crosspoint connection	Connection between any GPIO combination via analog multiplexer bus.
Differential non-linearity	Ideally, any two adjacent digital codes correspond to output analog voltages that are exactly one LSB apart. Differential non-linearity is a measure of the worst case deviation from the ideal 1 LSB step.
Hold time	Hold time is the time following a clock event during which the data input to a latch or flip-flop must remain stable in order to guarantee that the latched data is correct.
I^2C	It is a serial multi-master bus used to connect low speed peripherals to MCU.
Integral nonlinearity	It is a term describing the maximum deviation between the ideal output of a DAC/ADC and the actual output level.
Latch up current	Current at which the latch up test is conducted according to JESD78 standard (at 125 °C)
Power supply rejection ratio (PSRR)	The PSRR is defined as the ratio of the change in supply voltage to the corresponding change in output voltage of the device.
Scan	The conversion of all sensor capacitances to digital values.
Setup time	Period required to prepare a device, machine, process, or system for it to be ready to function.
Signal-to-noise ratio	The ratio between a capacitive finger signal and system noise.
SPI	Serial peripheral interface is a synchronous serial data link standard.

Reference Documents

- Technical reference manual for CY8C20xx6 devices
- In-system Serial Programming (ISSP) protocol for 20xx6 – AN2026C
- Host Sourced Serial Programming for 20xx6 devices – AN59389

Document History Page

Document Title: CY8C20336H/CY8C20446H Haptics Enabled CapSense® Controller Document Number: 001-56223				
Revision	**ECN**	**Origin of Change**	**Submission Date**	**Description of Change**
**	2787411	VZD/AESA	10/15/2009	New datasheet.
*A	3016550	KEJO/KPOL	08/26/2010	Added CY8C20346H part. Updated 24-pin QFN and 32-pin QFN package diagrams. Content and format updated to match latest template.
*B	3089844	JPM	11/18/10	In Table 26, modified T_{LOW} and T_{HIGH} min values to 42. Updated T_{SS_HIGH} min value to 50; removed max value.
*C	3180479	YVA	02/23/11	Removed CY8C20346H part Changed title from CapSense Applications to Haptics Enabled CapSense Controller Updated Table 29 with Time at Maximum Temperature information
*D	3638625	YLIU/BVI	06/06/2012	Updated F_{SCLK} parameter in the SPI Slave AC Specifications table Updated Getting Started and Designing with PSoC Designer sections. Included Development Tools. Updated Software under Development Tool Selection section. Updated F_{SCLK} parameter in the Table 26, “SPI Slave AC Specifications,” on page 24. Changed t_{OUT_HIGH} to t_{OUT_H} in Table 25, “SPI Master AC Specifications,” on page 23 Updated package diagrams: 001-13937 to *D 001-13191 to *F
*E	3822568	DST	11/27/2012	Updated package diagrams: 001-13937 to *E 001-42168 to *E 001-13191 to *G